

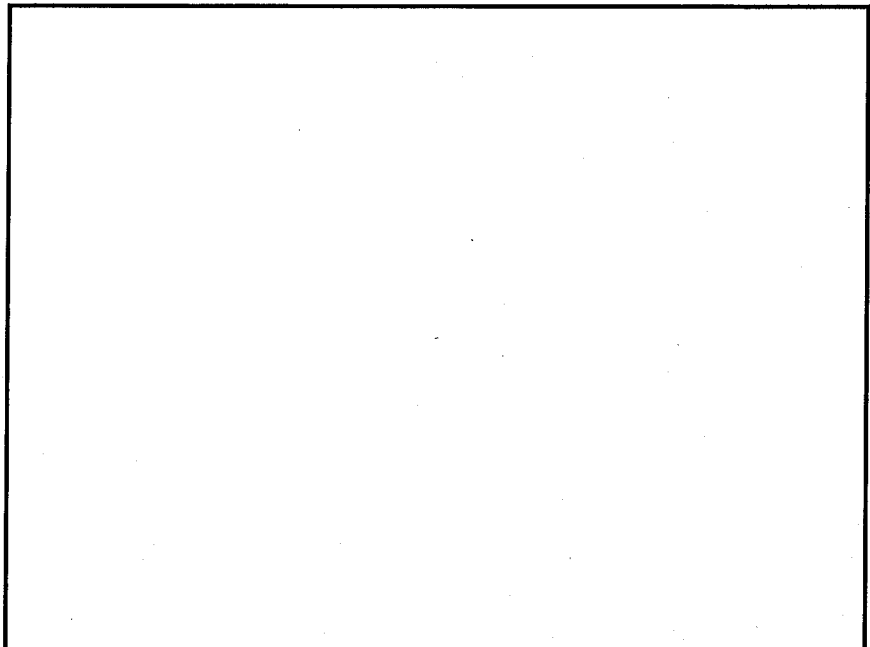
Tentative

CM100DY-24A

Pre.	K. Miki, H. Kuroki	Rev	
Apr.	T. Furuta 08-sep-'03		

HIGH POWER SWITCHING USE

CM100DY-24A	
●I <sub>c</sub> .....	100A
●V <sub>CES</sub> .....	1200V
●Insulated Type	
●2-elements in a pack	



APPLICATION

AC drive inverters & Servo controls, etc

ABSOLUTE MAXIMUM RATINGS (T<sub>j</sub> = 25 °C)

Symbol	Item	Conditions	Ratings	Units
V <sub>CES</sub>	Collector-emitter voltage	G-E Short	1200	V
V <sub>GES</sub>	Gate-emitter voltage	C-E Short	±20	V
I <sub>c</sub>	Collector current	DC, T <sub>c</sub> =84 °C *1	100	A
I <sub>CM</sub>		Pulse ②	200	
I <sub>E</sub> ①	Emitter current		100	A
I <sub>EM</sub> ①		Pulse ②	200	
P <sub>C</sub> ③	Maximum collector dissipation	T <sub>c</sub> = 25 °C *1	672	W
T <sub>j</sub>	Junction temperature		-40~+150	°C
T <sub>stg</sub>	Storage temperature		-40~+125	°C
Viso	Isolation voltage	Main terminal to base plate, AC 1 min.	2500	V
-	Torque strength	Main terminal M5	2.5 ~ 3.5	N·m
-	Torque strength	Mounting holes M6	3.5 ~ 4.5	N·m
-	Weight	Typical value	310	g

ELECTRICAL CHARACTERISTICS ( $T_j = 25\text{ }^\circ\text{C}$ )

Symbol	Item	Conditions	Min.	Typ.	Max.	Units
$I_{CES}$	Collector cutoff current	$V_{CE}=V_{CES}, V_{GE}=0V$	—	—	1	mA
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C=10mA, V_{CE}=10V$	6	7	8	V
$I_{GES}$	Gate leakage current	$V_{GE}=V_{GES}, V_{CE}=0V$	—	—	0.5	$\mu A$
$V_{CE(sat)}$	Collector to emitter saturation voltage	$T_j=25\text{ }^\circ\text{C}$   $I_C=100A$	—	2.1	3.0	V
		$T_j=125\text{ }^\circ\text{C}$   $V_{GE}=15V$	—	2.4	—	
$C_{ies}$	Input capacitance	$V_{CE}=10V$ $V_{GE}=0V$	—	—	17.5	nF
$C_{oes}$	Output capacitance		—	—	1.5	
$C_{res}$	Reverse transfer capacitance		—	—	0.34	
$Q_G$	Total gate charge	$V_{CC}=600V, I_C=100A, V_{GE}=15V$	—	500	—	nC
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600V, I_C=100A$ $V_{GE1}=V_{GE2}=15V$ $R_G=3.1\Omega$ , Inductive load switching operation	—	—	100	ns
$t_r$	Turn-on rise time		—	—	70	
$t_{d(off)}$	Turn-off delay time		—	—	400	
$t_f$	Turn-off fall time		—	—	350	
$t_{rr}$ ①	Reverse recovery time		$I_E=100A$	—	—	
$Q_{rr}$ ①	Reverse recovery charge		—	5.0	—	$\mu C$
$V_{EC}$ ①	Emitter-collector voltage	$I_E=100A, V_{GE}=0V$	—	—	3.8	V
$R_{th(j-c)Q}$	Thermal resistance	IGBT part (1/2 module) *1	—	—	0.186	$^\circ\text{C/W}$
$R_{th(j-c)R}$		FWDi part(1/2 module) *1	—	—	0.34	
$R_{th(c-f)}$	Contact thermal resistance	Case to fin, Thermal compound Applied (1/2module) *1 *2	—	0.022	—	
$R_G$	External gate resistance		3.1	—	42	$\Omega$

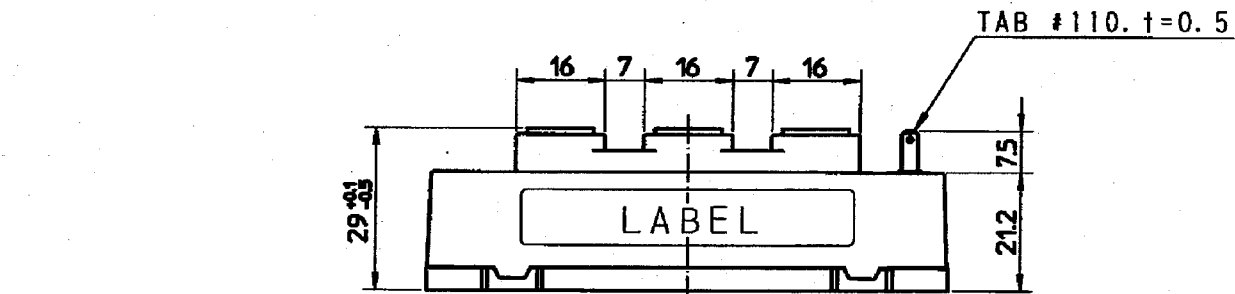
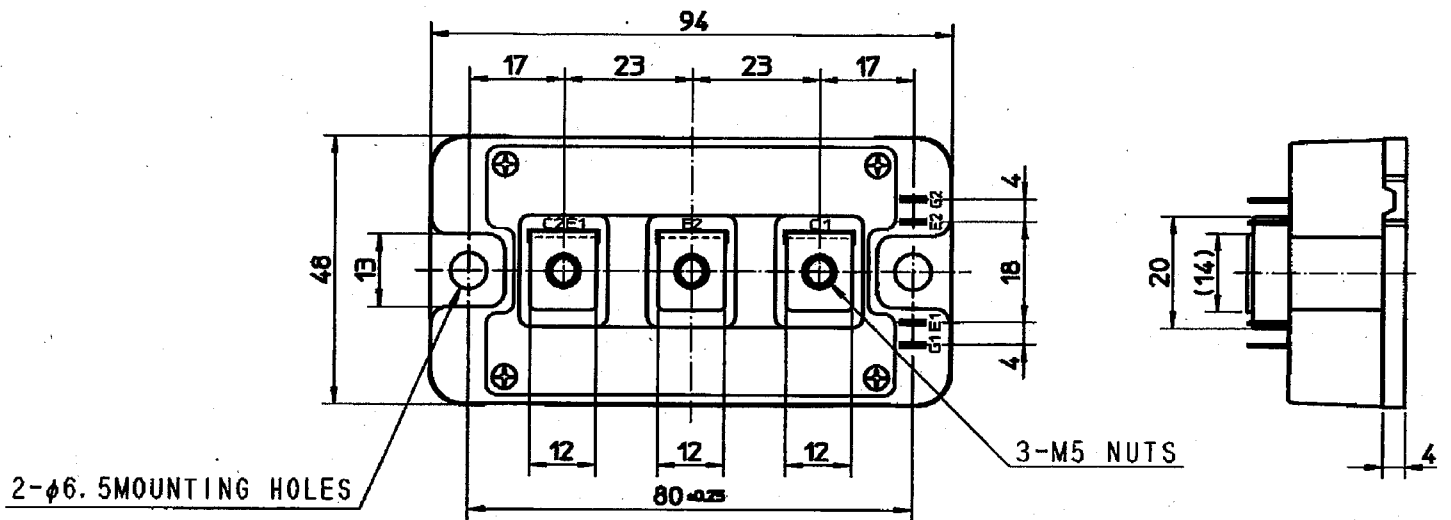
\*1:  $T_c, T_f$  measured point is just under the chips.

\*2: Typical value is measured by using Shin-etsu Silicone "G-746".

- ①  $I_E, V_{EC}, t_{rr}$  &  $Q_{rr}$  represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).
- ② Pulse width and repetition rate should be such that the device junction temp. ( $T_j$ ) dose not exceed  $T_{jmax}$  rating.
- ③ Junction temperature ( $T_j$ ) should not increase beyond  $150^\circ\text{C}$ .
- ④ Pulse width and repetition rate should be such as to cause neglible temperature rise.

OUTLINE DRAWING

Dimensions in mm



CIRCUIT DIAGRAM

